Material Composition Specification

CSP3.5X2 Case

Central Semiconductor™

Device average mass . . . . **7.79 mg**
Fluctuation margin . . . . **+/-10%**

Comp	Material		Substance	CAS No.	Substance		
	Weight (mg)	(%wt)			(%wt-mg)	(%wt)	(ppm)
Encapsulant	1.32826	1.71%	C_5H_9NO	872-50-4	2.78935e-05	0.00036%	3.581101163
			Glycol	109-17-1	0.053130543	0.68%	6821.145073
			CH_3OH	67-56-1	0.000104933	0.00%	13.47176152
			Other	Proprietary	0.079562987	1.02%	10214.66475
Die attach	0.327	0.48%	Ti	7440-32-6	0.004161295	0.05%	534.2462687
			Cu	7440-50-8	0.032993121	0.42%	4235.809702
Plating	5.71627	7.34%	Cu	7440-50-8	0.571627397	7.34%	73388.17222
Solder ball	1.722631	22.12%	Sn	7440-31-5	1.592916985	20.45%	204506.0587
			Ag	7440-22-4	0.041343147	0.53%	5307.824601
			Ni	7440-02-0	0.088198713	1.13%	11323.35915
Wafer	5.325027	68.36	Si	Proprietary	5.32502733	68.37%	683651.6667
Total	7.79	100%	n/a	Proprietary	7.789094343	100%	1000000.00

R0 (13-March 2024)